503138929 01/16/2015

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
CLEMENT HSINGJEN WANN	10/05/2011
LING-YEN YEH	10/05/2011
CHI-YUAN SHIH	10/12/2011
YI-TANG LIN	10/11/2011
CHIH-SHENG CHANG	10/11/2011
CHI-WEN LIU	10/13/2011

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN RD. VI, HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300

PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	14598276	

CORRESPONDENCE DATA

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NAME OF SUBMITTER:	RANDY A. NORANBROCK
SIGNATURE:	/Randy A. Noranbrock/
DATE SIGNED:	01/16/2015

PATENT 503138929 REEL: 034733 FRAME: 0262

Total Attachments: 2 source=efiledassgn#page1.tif source=efiledassgn#page2.tif

PATENT REEL: 034733 FRAME: 0263

ASSIGNMENT

In consideration of the premises and other	good and valuable	consideration in	ı hand paid,	the receipt an	d sufficiency	of
which is hereby acknowledged, the undersigned,				_	_	

1) Clement Hsingjen WANN 4) Yi-Tang LIN 2) Ling-Yen YEH 5) Chih-Sheng CHANG

Chi-Yuan SHIH 6) Chi-Wen LIU

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. having a place of business at No.

8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

SELECTIVE FIN-SHAPING PROCESS USING PLASMA DOPING AND ETCHING FOR 3-

DIMENSIONAL TRANSISTOR APPLICATIONS

for which an application for United States Letters Patent was filed on United States Patent Application No. 13/273, 527; or _____, and identified by (a)

(b) for which an application for United States Letters Patent was executed on

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) Clerk WANN
Name: Clement Hsingjen WANN

2) V Lugar Jul Name: Ling-Yen YEH

V 10/5/11
Date:

V [0/5/11 Date: V [0/12/2011

PATENT REEL: 034733 FRAME: 0264

4) Vi-Tang Lin	1105/11/01
Name: Yi-Tang LIN	Date:
5) V Ath Shong Rang Name: Chih-Sheng CHANG	V 10/11/2011
Name: Chih-Sheng CHANG	Date:
6) V Chi-Wen Lin	10/13/2011
Name: Chi-Wen LIII	Data

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RECORDED: 01/16/2015